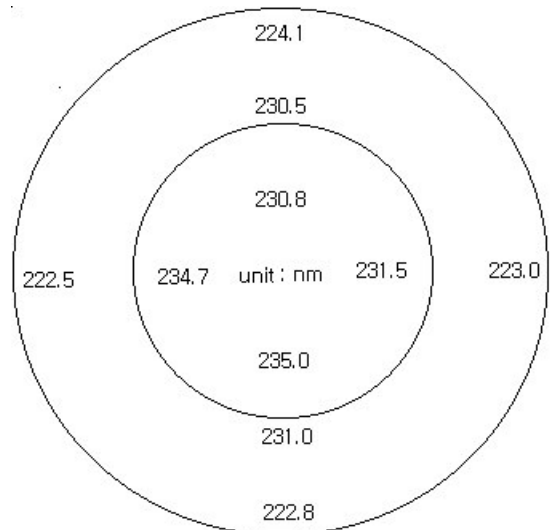


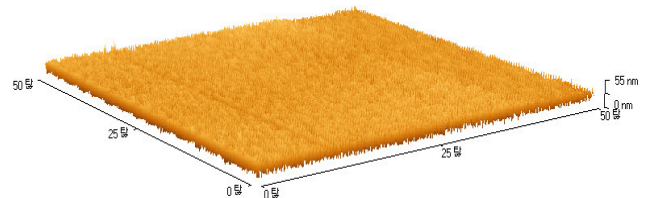
# ATS-PVD-Series Magnetron Sputter System with 4x6" Guns



Uniformity analysis of copper layer



AFM analysis of silica layer

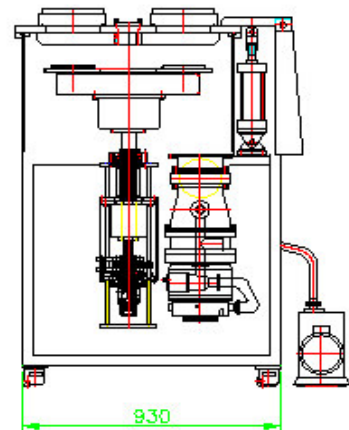
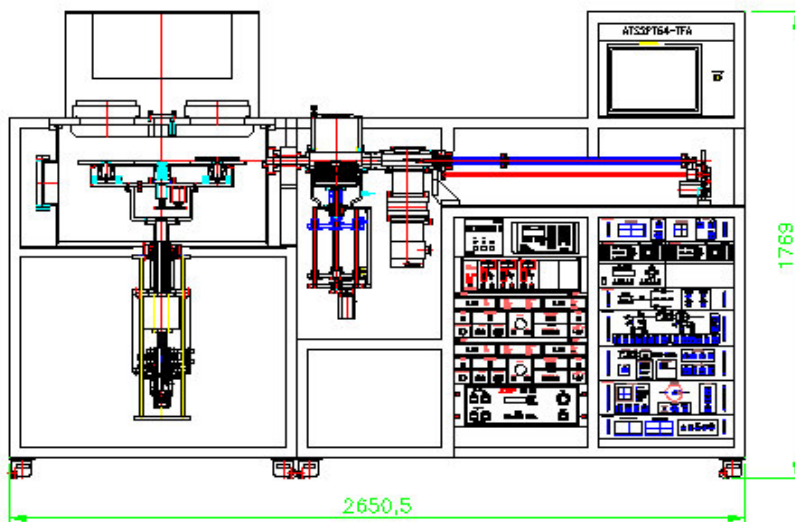
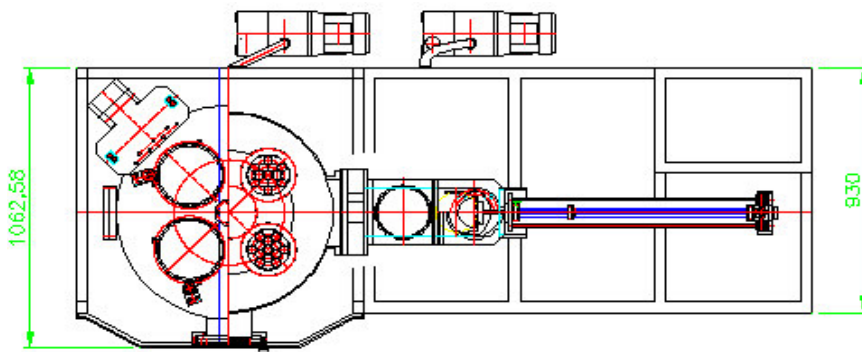


## Special Features

- ◆ 4x6" sputter system for R&D and small scale production
- ◆ Excellent thickness uniformity (below  $\pm 2.8\%$  for the layer of 228.6 nm in thickness)
- ◆ Highly smooth surface (RMS roughness of deposited layer: 25 Å)
- ◆ RF/DC magnetron sputter
- ◆ Automatic loading system
- ◆ Applications
  - Optical device
  - Passivation layer
  - Constantan materials

- ◆ Wafer capacity  
20 × 4"
- ◆ Average throughput  
Up to 100,000 wafers per year
- ◆ Dimension  
1575L X 1269H X 930W (mm<sup>3</sup>)
- ◆ Others  
Power: AC1.2kW for sputter source  
AC 600W for substrate bias voltage(13.56MHz)  
Gas : Ar / O<sub>2</sub> / H<sub>2</sub>  
Pump : rotary(980l/min) & turbo(1000l/s)

◇ Layout



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